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Autore	Campbell Jon C
Titolo	Geographic Analysis and Monitoring Program [[electronic resource]] / by Jon C. Campbell
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Autore	Agrawal Yash
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Altri autori (Persone)	MummaneniKavicharan SathyakamP. Uma
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Nota di contenuto	Chapter 1. An Efficient Model Order Reduction of Interconnects using Machine Learning for Timing Analysis -- Chapter 2. Delay and Overshoot Modelling of Asymmetric T-Tree Interconnects -- Chapter 3. Explicit Power-Delay Models for On-chip Copper and SWCNT Bundle Interconnects -- Chapter 4. Modelling and Analysis of Copper and Carbon Nanotube VLSI Interconnects -- Chapter 6. Through Silicon Vias for 3D Integration – A Mini Review -- Chapter 7. Neural Networks for Fast Design Space Exploration of On-chip Interconnect Networks -- Chapter 8. A Comprehensive Analysis of Emerging Variants of Swarm Intelligence for Circuits and Systems -- Chapter 9. PAM3: History, Algorithm, and Performance Comparison to NRZ, PAM4 -- Chapter 10. Emerging Interconnect Technologies for Integrated Circuit and Flexible Electronics -- Chapter 11. Contact and Interconnect Considerations for Organic and Flexible Electronics -- Chapter 12. Stretchable Interconnects: Materials, Geometry, Fabrication and Applications -- Chapter 13. Flexible Electronics: A Critical Review -- Chapter 14. Delay Analysis of Different Stretchable Interconnect Structures -- Chapter 15. Flexible Sensors for Plant Disease Monitoring -- Chapter 16.

Sommario/riassunto

This contributed book provides a thorough understanding of the basics along with detailed state-of-the-art emerging interconnect technologies for integrated circuit design and flexible electronics. It focuses on the investigation of advanced on-chip interconnects which match the current as well as future technology requirements. The contents focus on different aspects of interconnects such as material, physical characteristics, parasitic extraction, design, structure, modeling, machine learning, and neural network-based models for interconnects, signaling schemes, varying signal integrity performance analysis, variability, reliability aspects, associated electronic design automation tools. The book also explores interconnect technologies for flexible electronic systems. It also highlights the integration of sensors with stretchable interconnects to demonstrate the concept of a stretchable sensing network for wearable and flexible applications. This book is a useful guide for those working in academia and industry to understand the fundamentals and application of interconnect technologies.
